

DATA SHEET

HC 3052/HC 3053 HC 3054/HC 3057

MONOLITHIC CMOS SERIAL INTERFACE COFIDEC FAMILY

FEATURES

COMPLETE CODEC/FILTER (COFIDEC) FAMILY

• HC 3052 - µ-LAW WITH SHORT FRAME

SIGNALING (18 PIN)

- HC 3053 µ-LAW WITH BOTH SHORT AND LONG FRAME SIGNALING (20 PIN)
- HC 3054 μ-LAW WITHOUT SIGNALING (16 PIN)
- HC 3057 A-LAW (16 PIN)
- LOW OPERATION POWER (60 mW typical)

- LOW STANDBY POWER (1 mW typical)
- ± 5 V POWER SUPPLIES
- MEETS OR EXCEED ALL D3/D4 AND CCITT SPECIFICATIONS
- TTL COMPATIBLE DIGITAL INTERFACES
- PCM DATA SERIAL INPUT/OUTPUT
- SYNCHRONOUS OR ASYNCHRONOUS OPERATION



DESCRIPTION

The MHS CODEC/FILTER (COFIDEC) family includes A-Law and μ-Law monolithic CODEC/FILTERS implemented with double-poly CMOS technology.

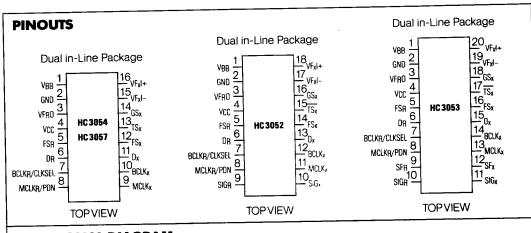
The transmit side of the device consists of:

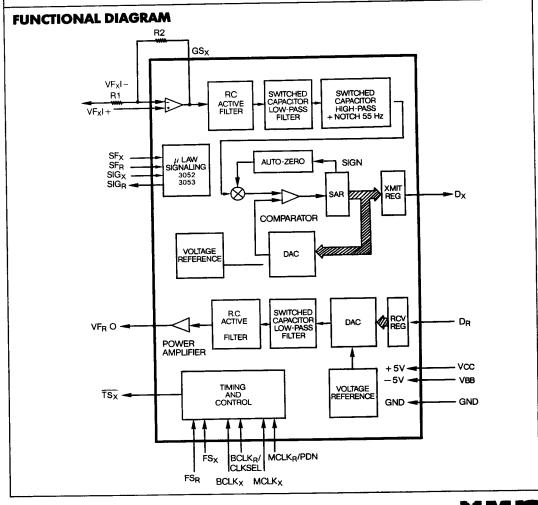
- an amplifier with external gain adjustment
- an RC active prefilter to eliminate high frequency noise
- a switched capacitor band-pass filter including a notch filter at 55 Hz to reject signals below 200 Hz and above 3400 Hz
- a charge redistribution coder which samples and encodes filtered signal in the companded $_\mu$ -Law or A-Law PCM format
- a precision voltage reference
- an internal auto-zero network to cancel the transmit offset.

The receive side of the device consists of:

- an expanding decoder (A-Law or μ -Law) to reconstruct the analog signal
- a switched-capacitor low-pass filter which corrects for the sinx/x response of the decoder output and rejects signals above 3400 Hz
- an RC active filter followed by a single ended power amplifier able to drive a 600 ohms load
- a precision voltage reference.
- The PCM word is transmitted/received in a serial format compatible with industry standard.
- The device is operated with two (transmit and receive) master clocks (1.536 MHz, 1.544 MHz or 2.048 MHz) which may be asynchronous.
- Also required are transmit and receive bit clocks which may vary from 64 KHz to 2.048 MHz and transmit and receive frame sync pulses.









PIN DESCRIPTION

HC 3052 PIN NO	HC 3053 PIN NO	HC 3054 HC 3057 PIN NO	NAME	FUNCTION
1	1	1	VBB	Negative power supply VBB = - 5 V.
2	2	2	GND	Ground.
3	3	3	VF _R O	Analog output of the receive filter.
4	4	4	Vcc	Positive power supply V _{CC} =+5 V.
5	5	5	FSR	Receive frame sync pulse.An 8 KHz pulse train which enables the PCM word to be shifted into the receive register.
6	6	6	DR	Receive data input. The receive register clocks in DR input with bit clock falling edge following an FSR rising edge.
7	7	7	BCLKR & CLKSEL	Bit clock which shifts DR input into the receive register. May vary from 64 KHz to 2.048 MHz. Alternatively may be a clock selection in synchronous mode. See table in functional description for synchronous operation.
8	8	8	MCLKR & PDN	Receive master clock must be 1.536 or 1.544 MHz. May be asynchronous with MCLKx and BCLKR. If MCLKR is low, the COFIDEC operates in synchronous mode. If MCLKR is tied high, the COFIDEC is powered down.
	9		SFR	When high during FSR, SFR indicates a receive signaling frame in long frame mode.
9	10		SIGR	The signaling bit appears at this ouptut after each receive signaling frame.
10	11		SIGX	Signaling data input. This input is inserted in place of LSB of PCM word during signaling frame.
	12		SFχ	When high during FSX, SFX indicates a transmit signaling frame in long frame mode.
11	13	9	MCLKX	Transmit master clock. Must be 1.536, 1.544 or 2.048 MHz. May be asynchronous with MCLKp. See table in functional description for synchronous operation.
12	14	10	BCLKX	Bit clock. May vary from 64 KHz to 2.048 MHz, but must be synchronous with MCLKx.
13	15	11	Dχ	Three-state PCM data output enabled by FSx.
14	16	12	FSχ	Transmit frame sync pulse. An 8 KHz pulse train which enables the PCM word to be shifted out through Dx with BCLKx.
15	17	13	TSχ	Open drain output. Pulled down during time slot.
16	18	14	GSχ	Analog output of transmit amplifier used to set the gain.
17	19	15	VFχI	Inverting input of transmit amplifier.
18	20	16	VF _X I+	Non inverting input of transmit amplifier.





FUNCTIONAL DESCRIPTION

POWER-UP

When power is first applied, power-on reset circuitry initializes the COFIDEC and places it into a power-down state. All non-essential circuits are deactivated and the $D_{\rm X}$ and $VF_{\rm R}O$ outputs are put in high impedance states. To power-up the device, a logical low level or clock must be applied to the MCLK_R/PDN pin and FS_x and/or FS_R pulses must be present. Thus, 2 power-down control modes are available. The first is to pull the MCLK_R/PDN pin high; the alternative is to hold both FS_x and FS_R inputs continuously low-the device will power-down approximately 2 ms after the last FS_x or FS_R pulse. The three state PCM data output, D_x, will remain in the high impedance state until the second FS_x pulse.

SYNCHRONOUS OPERATION

For synchronous operation, the same master clock and bit clock should be used for both the transmit and receive directions. In this mode, a clock must be applied to MCLK_X and the MCLK_R/PDN pin can be used as a power-down control. A low level on MCLK_R/PDN powers up the device and a high level powers down the device. In either case, MCLK_X will be selected as the master clock for both the transmit and receive circuits.

A bit clock must also be applied to BCLK $_{\rm R}$ and the BCLK $_{\rm R}$ /CLKSEL can be used to select the proper internal divider for a master clock of 1.536 MHz,1.544 MHz or 2.048 MHz. For 1.554 MHz operation, the device automatically compensates for the 193rd clock pulse each frame.

With a fixed level on the BCLK_R/CLKSELpin,BCLK_X will be selected as the bit clock for both the transmit and receive directions. *Table 1* indicates the frequencies of operation which can be selected, depending on the state of BCLK_R/CLKSEL.In this synchronous mode, the bit clock, BCLK_X, may be from 64 KHz to 2.048 MHz, but must be synchronous with MCLK_X.

Each FS_x pulse begins the encoding cycle and the PCM data from the previous encode cycle is shifted out of the enabled D_x output on the positive edge of BCLK_x. After 8 bit clock periods, the three state D_x output is returned to a high impedance state. With an FS_R pulse, PCM data is latched via the D_R input on the negative edge of BCLK_x (or BCLK_R ifrunning): FS_x and FS_R must be synchronous with MCLK_x/R.

ASYNCHRONOUS OPERATION

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Two asynchronous modes are allowed with excellent transmission performance:

1) MCLK_R is fully independent of MCLK_X and must be 2.048 MH_z for HC 3057 (A law) and 1.544 or 1.536 MH_z for HC 3052/3053/3054 (μ law) (freq MCLK_X=freq MCLK_R ± 50 ppm).

2) If required, $MCLK_x$ can be used as a master clock for both transmit and receive sections by applying static logic levels to the $MCLK_R/PDN$ pin.

In both modes, $BCLK_x$ and $BCLK_R$ may operate from 64 KH_z to 2.048 MH_z $BCLK_x$ must be synchronous

Table 1 - Selection of Master Clock Frequencies

	Master Frequency	
BCLK _R / CLKSEL	HC 3057	HC 3052 HC 3053 HC 3054
Clocked	2.048 MHz	1.536 MHz or
0	1.536MHz or 1.544 MHz	1.544 MHz 2.048 MHz
1 (or Open Circuit)		1.536 MHz or 1.544 MHz

with MCLK_x, but BCLK_R may be asynchronous with MCLK_R (freq BCLK_R = freq MCLK_R \pm 50 ppm). The degradation of the total signal to distortion ratio under all permitted asynchronous conditions does not exceed 0.5 dB as compared to the same measurement made with fully synchronous clocks.

SHORT FRAME SYNC OPERATION

The COFIDEC can utilize either a short frame sync pulse or a long frame sync pulse. Upon power initialization, the device assumes a short frame mode. In this mode, both frame sync pulses, FSx, and FSR, must be one bit clock period long, with timing relationships specified in Figure 2. With FSx high during a falling edge of BCLKx, the next rising edge of BCLK, enables the Dx three state output buffer, which will output the sign bit. The following seven rising edges clock out the remaining seven bits, and the next falling edge disables the Dx output. With FSR high during a falling edge of BCLK_R (BCLK_x in synchronous mode), the next falling edge of BCLK_R latches in the sign bit. The following seven falling edges latch in the seven remaining bits. All four devices may utilize the short frame sync pulse in synchronous or asynchronous operating mode.

LONG FRAME SYNC OPERATION

To use the long frame mode, both the frame sync pulses, FS_x and FS_R, must be three or more bit clock periods long, with timing relationships specified in Figure 3. Based on the transmit frame sync, FSx, the COFIDEC will sense whether short or long frame sync pulses are being used. For 64 KHz operation, the frame sync pulse must be kept low for a minimum of 160 ns. The D_x three state output buffer is enabled with the rising edge of FS_X or the rising edge of $BCLK_X$, whichever comes later, and the first bit clocked out is the sign bit. The following seven BCLK_x rising edges clock out the remaining seven bits. The Dx output is disabled by the falling BCLKx edge following the eighth rising edge, or by FS_x going low, whichever comes later. A rising edge on the receive frame sync pulse, FS_R, will cause the PCM data at D_R to be latched in on the next eight falling edges of BCLK_R (BCLK_X in synchronous mode). All four devices may utilize the long frame sync pulse in synchronous or asynchronous mode.



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SIGNALING

The HC 3052 and HC 3053 µ-law COFIDECs contain circuitry to insert and extract signaling information in the PCM data stream. The HC 3052 is intended for short frame sync applications, and the HC 3053 for long frame sync applications, although the HC 3053 may also be used in short frame sync applications. The HC3054 and HC3057 have no provision for signaling. Signaling for the HC 3052 is accomplished by applying a frame sync pulse two bit clock periods long, as shown in Figure 2. With FSx two bit clock periods long, the data present at SIGx input will be inserted as the LSB in the PCM data transmitted during that frame. With FSR two bit clock periods long, the LSB of the PCM data read into the Dp input will be latched and appear on the SIGR output pin until updated following the next signaling frame. The decoder will then interpret the lost LSB as "1/2" to minimize noise and distortion. This short frame signaling may also be implemented using the HC 3053, providing SFR and SFx are left open circuit or tied low. The HC 3052 is not capable of inserting or extracting signaling information in the long frame mode.

Signaling for the HC 3053 may be accomplished in either short or long frame sync mode. The short mode signaling is the same as the HC 3052. For long frame signaling, two additional frame sync pulses are required, SFx and SFR, which indicate transmit and receive signaling frames, respectively. With an SFx signaling frame sync, the data present at the SIGx input will be inserted as the LSB in the PCM data transmitted during that frame. With an SFR signaling frame sync, the LSB of the PCM data at DR will be latched and appear on the SIGR output pin until the

next signaling frame. The decoder will also do the "1/2" step interpretation to compensate for the loss of the LSR

TRANSMIT SECTION

The input of the transmit section is an operational amplifier whose gain can be externally adjusted. This amplifier exhibits low noise, wide bandwith and low offset voltage (1mV typical). The input amplifier drives an antialiasing RC active filter. The switched capacitor bandpass filter is split into a 5 th order elliptic low-pass filter and a 3rd order elliptic high-pass filter which includes a 55 Hz notch filter to guarantee excellent line (50 or 60 Hz) rejection. The structure of each filter is fully differential so that their performance is not affected by parasitic elements. The A/D converter is of a companding type according to A (HC 3057) or μ (HC 3052/3053/3054) coding laws.

RECEIVE SECTION

The receive section includes an expanding D/A converter according to A (HC 3057) or μ (HC 3052/3053/3054) coding laws. The decoder is followed by a 5 th order switched capacitor low-pass filter and an RC active filter.

As for the transmit part, the filters are fully differential. The output amplifier has a unity gain and can drive a $600 \, \Omega/500 \, \text{pF}$ load.

Separately trimmed voltage references are provided for transmit and receive sections respectively. Clocking circuits and internal power supplies are also fully independent. This arrangement greatly reduces crosstalk between the transmit and receive blocks and improves performance.





ELECTRICAL SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS

VCC to GND -0.3V to 7V VBB to GND +0.3V to -7V Voltage at any Digital Input or Output

VCC+0.3V to GND-0.3V

Voltage at any Analog Input or Output VCC + 0.3V to VBB - 0.3V Operating Temperature Range Storage Temperature Range -25 °C to 80 °C -65 °C to 150 °C Lead Temperature (Soldering 10 seconds) 300 °C

ELECTRICAL CHARACTERISTICS

Unless otherwise noted: $VCC=5.0V\pm5\%VBB=5V\pm5\%GND=OV$

 $T_A = 0$ °C to 70 °C: typical characteristics specified at $V_{CC} = 5.0$ V, $V_{BB} = -5.0$ V. $T_A = 25$ °C: all signals are referenced to GND

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
DIGITAL	NTERFACE					
VIL	Input Low Voltage				0.6	٧
VIH	Input High Voltage		2.2			
VOL	Output Low Voltage	DX , $I_L = 5.0 \text{mA}$ $SIGR$, $I_L = 1.0 \text{mA}$ TSX , $I_L = 3.2 \text{mA}$. Open Drain			0,4 0.4 0.4	V V
VOH	Output High Voltage	DX, IL=-5.0mA SIGR, IL=-1.0mA	2.4 2,4			V
IIL	Input Low Current (Note 1)	GND ≤ V _{IN} ≤ V _{IL} . All Digital Inputs	-10		10	μА
lН	Input High Current (Note 1)	VIH VIN VCC	-10		10	μA
loz	Output Current in High Impedance State	DX, GND≤ VO≤ VCC	-10		10	μА
ANALOG	INTERFACE WITH TRANSMIT	INPUT AMPLIFIER (ALL DEVICES)				,
IJXA.	Input Leakage Current	$-2.5V \le V \le +2.5V$, VF χ I + or VF χ I -	-200		200	nA
R _I XA	Input Resistance	$-2.5V \le V \le +2.5V$, $VF\chi I + or VF\chi I -$	10			MΩ
ROXA	Output Resistance	Closed Loop. Unity Gain		1	3	Ω
RLXA	Load Resistance	GSX	10			kΩ
CLXA	Load Capacitance	GSχ			50	pF
VOXA	Output Level	GSχRL=10k Ω	±2.8	±4.2		V
AVXA	Voltage Gain	VFxI+to GSx	5000			VV
FuXA	Unity Gain Bandwidth		1	2		MHz
VosXA	Offset Voltage		-20	1	20	mV
VCMXA	Common-Mode Voltage		-2.5		+ 2.5	V
CMRRXA	Common-Mode-Rejection Ratio		60	80		dB
PSRRXA	Power Supply Rejection Ratio		60	70		dB
ANALOG	INTERFACE WITH RECEIVE F	FILTER (ALL DEVICES)				<u></u>
RORF	Output Resistance	Pin VF _R O	<u> </u>	1	3	Ω
RLRF	Load Resistance	VFRO=± 2.5V	600			Ω
CLRF	Load Capacitance				500	pF
VOSRO	Output DC Offset Voltage		-100		100	mV
POWER	DISSIPATION (ALL DEVICES)			·		·
ICCO	Power-Down Current		<u> </u>	0.15	0.5	mA
IBBO	Power-Down Current			0.05	0.3	mA
ICC1	Active Current			6	9	mA
IBB1	Active Current			6	9	mA

Note 1: SFx, SFB: Internal pull down (2µ A typical) - BCLKR: Internal pull up (2µ A typical)



TRANSMISSION CHARACTERISTICS (ALL DEVICES)

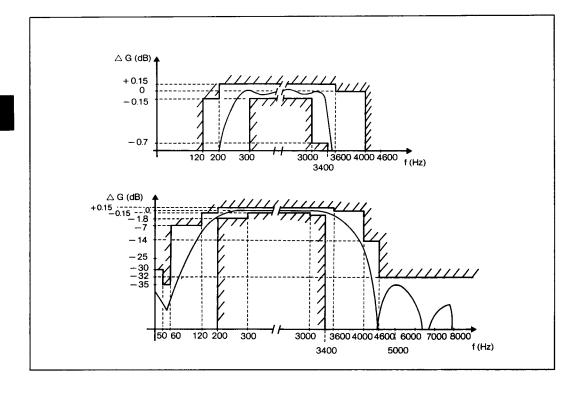
Unless otherwise specified: TA = 0 °C to 70 °C, VCC = 5V \pm 5%, VBB = -5V \pm -5%, GND=OV, f=1.02 kHz, VIN, = 0 dBm0, transmit input amplifier connected for unity-gain non-inverting.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
	JDE RESPONSE					
	Absolute Levels	Nominal 0 dBm0 Level is 4 dBm (600a). 0 dBm0 (all devices)		1.2277		Vrms
	Max Overload Levels	HC 3052, HC 3053, HC 3054 (3.17 dBm0) HC 3057 (3.14 dBm0)		2.501 2.492		VDC VDC
GXA	Transmit Gain, Absolute	TA=25 °C,VCC=5V,VBB=-5V Input at GSX=OdBm0 at 1020 Hz	-0.15		0.15	đB
GXATV	Absolute Transmit Gain Variation with Temperature and Supply Voltage	TA=0 °C to 70 °C VCC=5V±5%,VBB=-5V±-5%			± 0.15	dB
GXRL	Transmit Gain Variations with level	Sinusoidal Test Method Reference Level 10 dBm0 VFXI + 40 dBm0 to + 3 dBm0 VFXI + 50 dBm0 to 40 dBm0 VFXI + 55 dBm0 to 50 dBm0	0.2 -0.4 -1.2		0.2 0.4 1.2	dB dB dB
GRA	Receive Gain, Absolute	TA=25 °C,VCC=5V,VBB=-5V Input=Digital Code Sequence for OdBm0 Signal at 1020Hz	-0.15		0.15	dB
GRATV	Absolue receive Gain Variation with Temperature and Supply Voltage	T _A =0 °C to 70 °C V _{CC} =5V±5 %V _{BB} ±5V±5 %			± 0.15	dB
GRRL	Receive Gain Variations with Level	Sinusoidal Test Method : Reference Input PCM Code Corresponds to an ideally Encoded - 10 dBm0 Signal				
		PCM Level =40 dBm0 to + 3 dBm0 PCM Level = -50 dBm0 to - 40 dBm0 PCM Level = -55 dBm0 to = 50 dBm0	-0.2 -0.4 -1.2		+ 0.2 + 0.4 + 1.2	dB dB dB
1/20	Receive Output Drive Level	R _I = 600 Ω	2.5		2.5	V
VRO	PE DELAY DISTORTION WITH F		2.0		2.0	V
DXA	Transmit Delay, Absolute	f=1600 Hz		290	315	μS
DXR	Transmit Delay, Relative to DXA	f= 500 Hz - 600 Hz f= 600 Hz - 800 Hz f= 800 Hz - 1000 Hz f= 1000 Hz - 1600 Hz f= 1600 Hz - 2600 Hz f= 2600 Hz - 2800 Hz f= 2800 Hz - 3000 Hz		140 100 50 20 60 80 140	220 145 75 50 100 110 200	5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5 5
DRA	Receive Delay, Absolute	f= 750 Hz		160	180	μS
DRR	Receive Delay, Relative to DRA	f= 500 Hz - 1600 Hz f= 1600 Hz - 2600 Hz f= 2600 Hz - 2800 Hz f= 2800 Hz - 3000 Hz		40 90 120 140	60 120 140 175	µS µS µS



Unless otherwise specified: $T_A = 0$ °C to 70 °C, $V_{CC} = 5V \pm 5$ %, $V_{BB} = -5V \pm 5$ %, GND = 0V, f = 1.02 kHz, $V_{IN} = 0$ dBm0, transmit input amplifier connected for unity gain non-inverting.

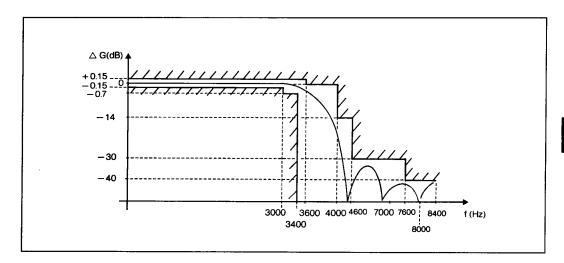
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
TRANSM	IIT SECTION TRANSFER CH	IARACTERISTICS				
GXR	Transmit Gain Relative to Gain at 820 Hz (0dBm0)	f= 50 Hz - 60 Hz f= 60 Hz - 120 Hz f= 120 Hz - 200 Hz f= 200 Hz - 3000 Hz f= 3000 Hz - 3400 Hz f= 3400 Hz - 3600 Hz f= 3600 Hz - 4000 Hz f= 4000 Hz - 4600 Hz f= 4600 Hz and Up	- 1.8 - 0.15 - 0.7		-35 -7 -0.15 +0.15 +0.15 +0.15 0 -14 -32	dB dB





Unless otherwise specified : $T_A = 0^{\circ}C$ to $70^{\circ}C$, $V_{CC} = 5V \pm 5$ %, $V_{BB} = -5V \pm 5$ %, GND = 0V, f = 1.02 kHz, $V_{IN} = 0$ dBm0, transmit input amplifier connected for unity gain non-inverting.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
RECEIVE	SECTION TRANSFER CHA	RACTERISTICS				
GRR	Receive Gain Relative to Gain at 820 Hz (0dBm0)	f= 0 Hz - 3000 Hz f=3000 Hz - 3400 Hz f=3400 Hz - 3600 Hz f=3600 Hz - 4000 Hz f=4000 Hz - 4600 Hz	- 0.15 - 0.7		+0.15 +0.15 +0.15 0 -14	88888 88888
SOS	Spurious Out-of-Band Signals at the channel Output	Image Signals at VF _R O: f=4600 Hz to 7600 Hz f=7600 Hz to 8400 Hz			-30 -40	8 8 8





TRANSMISSION CHARACTERISTICS (continued) Unless otherwise specified : $T_A = 0$ °C to 70 °C, $V_{CC} = 5V \pm 5$ %, $V_{BB} = -5V \pm 5$ %, $V_{CC} = 5V \pm$

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
NOISE	, r			<u> </u>		
NXC	Transmit Idle Channel Noise, C Message Weighted	HC 3052, HC 3053, HC 3054 VFxI *= OV		12	15	dBmC0
NXP	Transmit Noise, P Message Weighted	HC 3057 Note 1 VF _X I ⁻ = OV Note 2		-74 -70	-69 -67	dBm0p dBm0p
NRC	Receive Idle Channel Noise C Message Weighted	HC 3052, HC 3053, HC 3054 PCM Code equals alternating Positive and Negative Zero		8	11	dBrnC0
NRP	Receive Idle Channel Noise P Message Weighted	HC 3057 PCM Code equals Positive Zero		-82	-79	dBm0p
NRS	Noise, Single Frequency	f=0 KHz to 100 KHz, Loop Around Measurement, VFxI ⁻ =0 Vrms			-53	dBm0
POWER	SUPPLY REJECTION					
PPSRX	Positive Power Supply Rejection Transmit	$VF\chi I^-=0 Vrms$ VCC=5.0 VDC+100 mVrms f=0-50 KHz	40_			dBC
NPSRX	Negative Power Supply Rejection Transmit	VFXI ⁺ =0 Vrms VBB=-5.0 VDC + 100 mVrms f=0-50 KHz	40			dBC
PPSRR	Positive Power Supply Rejection Receive	PCM Code equals Positive Zero $V_{CC} = 5.0 V_{DC} + 100 \text{mVrms}$ $f = 0.4000 \text{Hz}$ $f = 0 - 50 \text{KHz}$	40 25			dBC dB
NPSRR	Negative Power Supply Rejection Receive	PCM Code equals Positive Zero VBB = - 5.0 VDC + 100 mVrms f = 0 - 4000 Hz f = 0 - 50 KHz	40 25			dBC dB
DISTORT	TON					
STD _{X/R}	Signal to Total Distortion Transmit or Receive Channel	Sinusoidal Test Method Level = 3.0 dBm0 = 0dBm0 to - 30 dBM0 =- 40 dBm0 XMT RCV =- 55 dBm0 XMT RCV	33 36 29 30 14 15			dBC dBC dbc dBC dBC dBC dBC
SFDX	Single Frequency Distortion Transmit				-46	dB
SFDR	Single Frequency Distortion Receive				-46	dB
IMD	Intermodulation Distortion	Loop Around Measurement. VFXI' =- 4 dBm0 to - 21 dBm0, two frequencies in the range 300 Hz to 3 400 Hz			-41	dB
CROSST	TALK					
CT _X -R	Transmit to Receive Crosstalk OdBm0 Transmit Level	f=300 Hz-3400 Hz DR=Steady PCM Code		-90	-75	dB
CT _R -X	Receive to Transmit Crosstalk odBm0 Receive Level	f=300 Hz - 3 400 Hz VFXI' = OV		-90	-70	dB

Note 1: Quantization Noise, measured by extrapolation from the distortion result.

Note 2: Idle Channel Noise, due to alternating sign bit of a perfectly zeroed encoder.



TIMING SPECIFICATIONS Unless otherwise specified TA = 0 °C to 70 °C, VCC = 5V \pm 5 %, VBB = - 5V \pm 5 %, GND = 0V

SYMBOL	PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
1/tpM	Frequency of Master Clocks	Depends on the Device Used and the BCLKR/CLKSEL Pin MCLKX and MCLKR		1.536 1.544 2.048		MHz MHz MHz
tWMH	Width of Master Clock High	MCLK _X and MCLK _R	160			ns
tWML	Width of Master Clock Low	MCLKX and MCLKR	160			ns
tsbfm	Set-Up Time from BCLKX High (and FSX in Long Frame Sync Mode) to MCLKX Falling Edge	First Bit Clock after the Leading Edge of FSX	100			ns
tWBH	Width of Bit Clock High	V _{IH} = 2.2V	160			ns
tWBL	Width of Bit Clock Low	V _{IL} =0.6V	160			ns
tHBF	Holding Time from Bit Clock Low to Frame Sync	Long Frame Only	0			ns
tHOLD	Holding Time from Bit Clock High to Frame Sync	Short Frame Only	0			ns
tSBF	Set-Up Time from Frame Sync to Bit Clock Low	Long Frame Only	80			ns
tDBD	Delay Time from BCLKX High to Data Valid	Load = 150 pF plus 2 LSTTL loads	0		140	ns
tXDP	Delay Time to TSX Low	Load=150 pF plus 2 LSTTL loads			140	ns
tDZC	Delay Time from BCLKx Low to Data Output Disabled	C _L =0 pF to 150 pF	50		165	ns
tDZF	Delay Time to Valid Data from FSx or BCLKx, Whichever Comes later	CL=0 pF to 150 pF	20		165	ns
tssff	Set-Up Time from SFX/R High to FSX/R	HC 3053 Only	60			ns
tssfb	Set-Up Time from Signal Frame Sync High to BCLKX/R Clock	HC 3053 Only	60	,		ns
tssgb	Set-UpTimefromSIGxtoBCLKx	HC 3052 and HC 3053	100			ns
thbsg	Hold Time from BCLKx High to SIGx	HC 3052 and HC 3053	50			ns
tSDB	Set-Up Time from DRValid to BCLKR/X Low		50			ns
tHBD	Hold Time from BCLKR/X Low to DR Invalid		50			ns
thbsf	Hold Time from BCLKX/R Low to Signaling Frame Sync	HC 3053 Only	100			ns
tSF	Set-Up Time from FSX/R to BCLKX/R Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	50			ns
tHF	Hold Time from BCLKX/R Low to FSX/R Low	Short frame Sync Pulse (1 Bit Clock Period Long)	100			ns
thbFi	Hold Time from 3rd Period of Bit Clock Low to Frame Sync (FSX or FSR)	Long Fram Sync Pulse (from 3 to 8 Bit Clock Periods Long)	100			ns
tWFL	Minimum Width of the Frame Sync Pulse (Low Level)	64K Bit/s Operating Mode	160			ns



CONDITIONS

ELECTRICAL SPECIFICATIONS

ABSOLUTE MAXIMUM RATINGS

SVMBOL

VCC to GND VBB to GND -0.3V to 7V+0.3V to -7VVoltage at any Digital Input or Output

VCC + 0.3V to GND - 0.3V Voltage at any Analog Input or Output

VCC + 0.3V to VRR - 0.3VDARAMETER

-40 °C to 85 °C Operating Temperature Range Storage Temperature Range -65 °C to 150 °C Lead Temperature (Soldering 10 seconds) 300 °C

ELECTRICAL CHARACTERISTICS

Unless otherwise noted: VCC=5.0V±5%VBB=5V± 5% GND=OV

TA = -40 °C to 85 °C: typical characteristics specified at VCC=5.0V, VBB=-5.0V.TA=25 °C: all signals are referenced to GND

MIN TYP MAX UNITS

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
DIGITAL	INTERFACE					
VIL	Input Low Voltage				0.6	V
VIH	Input High Voltage		2.2			V
VOL	Output Low Voltage	DX, IL = 5.0mA SIGR, IL = 1.0mA TSX, IL = 3.2mA. Open Drain			0,4 0.4 0.4	V V
VOH	Output High Voltage	DX, IL =-5.0mA SIGR, IL =-1.0mA	2.4 2,4			V V
ΙL	Input Low Current (Note 1)	GND ≤ V _{IN} ≤ V _{IL} . All Digital Inputs	-10		10	μA
lн	Input High Current (Note 1)	VIH ≤ VIN ≤ VCC	-10		10	μΑ
loz	Output Current in High Impedance State	DX, GND ≤ VO ≤ VCC	-10		10	μА
ANALOG	INTERFACE WITH TRANSMIT	INPUT AMPLIFIER (ALL DEVICES)				
IJXA.	Input Leakage Current	$-2.5V \le V \le +2.5V$, VF χ I + or VF χ I -	-200		200	nA
R _I XA	Input Resistance	$-2.5V \le V \le +2.5V$, VF χ I + or VF χ I -	10			ΜΩ
ROXA	Output Resistance	Closed Loop. Unity Gain		1	3_	Ω
RLXA	Load Resistance	GSX	10			kΩ
CLXA	Load Capacitance	GSX			50	pF
VOXA	Output Level	GSχRL=10k Ω	±2.8	±4.2		V
AVXA	Voltage Gain	VF _X I+to GS _X	5000			VV
FUXA	Unity Gain Bandwidth		1	2		MHz
VosXA	Offset Voltage		-20	1	20	m۷
VCMXA	Common-Mode Voltage		-2.5		+ 2.5	V
CMRRXA	Common-Mode-Rejection Ratio		60	80		dB
PSRRXA	Power Supply Rejection Ratio		60	70		dB
ANALOG	INTERFACE WITH RECEIVE F	ILTER (ALL DEVICES)				
RORF	Output Resistance	Pin VF _R O		1	3	Ω
RLRF	Load Resistance	VFRO=± 2.5V	600			Ω
CLRF	Load Capacitance				500	pF
VOSRO	Output DC Offset Voltage		-100		100	m۷
POWER	DISSIPATION (ALL DEVICES)					
Icco	Power-Down Current			0.15	0.5	mA
IBBO	Power-Down Current			0.05	0.3	mA
ICC1	Active Current			6	9	mA
I _{BB1}	Active Current			6	9	mA

Note 1: SF_x, SF_B: Internal pull down (2µ A typical) - BCLK_R: Internal pull up (2µ A typical)





TRANSMISSION CHARACTERISTICS (ALL DEVICES)

Unless otherwise specified: TA = $-40\,^{\circ}$ C to 85 °C,VCC = 5V $\pm 5\,\%$, VBB = -5V $\pm -5\,\%$, GND = OV,f = 1.02 kHz,V_{IN} = 0 dBm0, transmit input amplifier connected for unity-gain non-inverting.

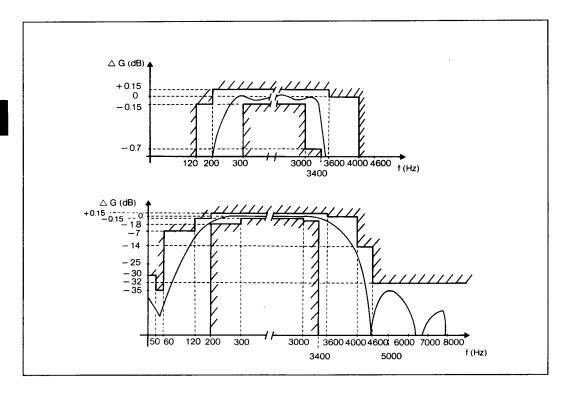
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
AMPLIT	UDE RESPONSE		•			
	Absolute Levels	Nominal 0 dBm0 Level is 4 dBm (600 α). 0 dBm0 (all devices)		1.2277		Vrms
	Max Overload Levels	HC 5552, HC 5553, HC 5554 (3.17 dBm0) HC 5557 (3.14 dBm0)		2.501 2.492		VDC VDC
GXA	Transmit Gain, Absolute	TA=25 °C,VCC=5V,VBB=-5V Input at GSX=OdBm0 at 1020 Hz	-0.15		0.15	dB
GXATV	Absolute Transmit Gain Variation with Temperature and Supply Voltage	$T_A = -40$ °C to +85 °C $V_{CC} = 5V \pm 5$ %, $V_{BB} = -5V \pm -5$ %			± 0.15	dB
GXRL	Transmit Gain Variations with level	Sinusoidal Test Method Reference Level 10 dBm0 VFXI+=-40 dBm0 to +3 dBm0 VFXI+=-50 dBm0 to 40 dBm0 VFXI+=-55 dBm0 to 50 dBm0	0.2 -0.4 -1.2		0.2 0.4 1.2	dB dB dB
GRA	Receive Gain, Absolute	TA=25 °C,VCC=5V,VBB=-5V Input=Digital Code Sequence for OdBm0 Signal at 1020Hz	-0.15		0.15	dB
GRATV	Absolue receive Gain Variation with Temperature and Supply Voltage	$T_A = -40$ °C to +85 °C $V_{CC} = 5V \pm 5$ % $V_{BB} \pm 5V \pm 5$ %			± 0.15	dB
GRRL	Receive Gain Variations with Level	Sinusoidal Test Method: Reference Input PCM Code Corresponds to an ideally Encoded - 10 dBm0 Signal PCMLevel= -40 dBm0 to +3 dBm0	0.2		0.2	dB
		PCM Level = -50 dBm0 PCM Level = -55 dBm0 to -50 dBm0 to -55 dBm0 to -55 dBm0	-0.4 -1.2		+0.4 +1.2	dB dB
VRO	Receive Output Drive Level	R _L =600 Ω	2.5		2.5	٧
ENVELO	PE DELAY DISTORTION WITH F	REQUENCY				
DXA	Transmit Delay, Absolute	f=1600 Hz		290	315	μS
DXR	Transmit Delay, Relative to DXA	f= 500 Hz - 600 Hz f= 600 Hz - 800 Hz f= 800 Hz - 1000 Hz f= 1000 Hz - 1600 Hz f= 1600 Hz - 2600 Hz f= 2600 Hz - 2800 Hz f= 2800 Hz - 3000 Hz		140 100 50 20 60 80 140	220 145 75 50 100 110 200	4 4 4 4 4 4 4 6 9 9 9 9 9 9 9
DRA	Receive Delay, Absolute	f= 750 Hz		160	180	μS
DRR	Receive Delay, Relative to DRA	f= 500 Hz - 1600 Hz f=1600 Hz - 2600 Hz f=2600 Hz - 2800 Hz f=2800 Hz - 3000 Hz		40 90 120 140	60 120 140 175	18 18 19 19 19 19 19





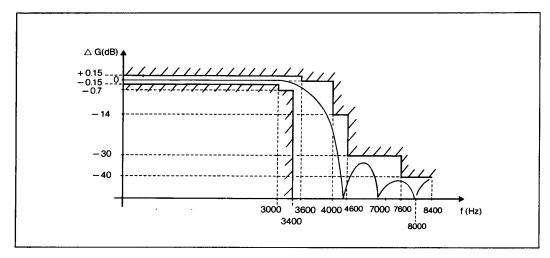
Unless otherwise specified: TA = -40 °C to 85 °C, VCC = $5V \pm 5\%$, VBB = $-5V \pm 5\%$, GND = 0V, f = 1.02 kHz, VIN = 0 dBm0, transmit input amplifier connected for unity gain non-inverting.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
TRANSM	IT SECTION TRANSFER CH	IARACTERISTICS				
GXR	Transmit Gain Relative to Gain at 1020 Hz (0dBm0)	f= 50 Hz - 60 Hz f= 60 Hz - 120 Hz f= 120 Hz - 200 Hz f= 200 Hz - 3000 Hz f= 300 Hz - 3000 Hz f= 3000 Hz - 3400 Hz f= 3400 Hz - 3600 Hz f= 3600 Hz - 4000 Hz f= 4000 Hz - 4600 Hz f= 4600 Hz and Up	- 1.8 - 0.15 - 0.7		-35 -7 -0.15 +0.15 +0.15 +0.15 0 -14 -32	dB dB



Unless otherwise specified : TA = -40° C to 85° C, VCC = 5V \pm 5 %, VBB = -5V \pm 5 %, GND = 0V,f = 1.02 kHz, V_{IN} = 0 dBm0, transmit input amplifier connected for unity gain non-inverting.

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS	
RECEIVE SECTION TRANSFER CHARACTERISTICS							
GRR	Receive Gain Relative to Gain at 1020 Hz (0dBm0)	f= 0 Hz - 3000 Hz f=3000 Hz - 3400 Hz f=3400 Hz - 3600 Hz f=3600 Hz - 4000 Hz f=4000 Hz - 4600 Hz	-0,15 -0,7		+0.15 +0.15 +0.15 0 -14	ав ав ав ав	
SOS	Spurious Out-of-Band Signals at the channel Output	Image Signals at VFRO: f = 4600 Hz to 7600 Hz f = 7600 Hz to 8400 Hz			-30 -40	dB dB dB	





TRANSMISSION CHARACTERISTICS (continued)Unless otherwise specified: $T_A = -40 \,^{\circ}\text{C}$ to $85 \,^{\circ}\text{C}$, $V_{CC} = 5V \pm 5 \,^{\circ}\text{C}$, $V_{BB} = -5V \pm 5 \,^{\circ}\text{C}$, $V_{CD} = 5V \pm 5 \,$

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
NOISE						
NXC	Transmit Idle Channel Noise, C Message Weighted	HC 3052, HC 3053, HC 3054 VFXI *= OV		12	15	dBmC0
NXP	Transmit Noise, P Message Weighted	HC 3057 Note 1 VF _X I ⁻ =OV Note 2		-74 -70	-69 -67	dBm0p dBm0p
NRC	Receive Idle Channel Noise C Message Weighted	HC 3052, HC 3053, HC 3054 PCM Code equals alternating Positive and Negative Zero		8	11	dBrnCC
NRP	Receive Idle Channel Noise P Message Weighted	HC 3057 PCM Code equals Positive Zero		-82	-79	dBm0p
NRS	Noise, Single Frequency	f=0 KHz to 100 KHz, Loop Around Measurement, VFxI*=0 Vrms			-53	dBm0
POWER	SUPPLY REJECTION					
PPSRX	Positive Power Supply Rejection Transmit	$VFXI^*=0$ Vrms VCC=5.0 VpC + 100 mVrms f=0-50 KHz	40			dBC
NPSRX	Negative Power Supply Rejection Transmit	VFXI ⁺ = 0 Vrms VBB = - 5.0 VDC + 100 mVrms f= 0 - 50 KHz	40			dBC
PPSRR	Positive Power Supply Rejection Receive	PCM Code equals Positive Zero V _{CC} = 5.0 V _{DC} + 100 mVrms f=0.4000 Hz f=0-50 KHz	40 25			dBC dB
NPSRR	Negative Power Supply Rejection Receive	PCM Code equals Positive Zero VBB = -5.0 VDC + 100 mVrms f=0-4000 Hz f=0-50 KHz	40 25			dBC dB
DISTOR	TION					
STD _{X/R}	Signal to Total Distortion Transmit or Receive Channel	Sinusoidal Test Method Level = 3.0 dBm0 = 0dBm0 to - 30 dBM0 =- 40 dBm0 XMT RCV =- 55 dBm0 XMT RCV	33 36 29 30 14 15			dBC dBC dbc dBC dBC dBC
SFDX	Single Frequency Distortion Transmit				-46	dB
SFDR	Single Frequency Distortion Receive				-46	dB
IMD	Intermodulation Distortion	Loop Around Measurement. VFXI' =- 4 dBm0 to - 21 dBm0, two frequencies in the range 300 Hz to 3 400 Hz			-41	d₿
CROSST	TALK					
CT _X -R	Transmit to Receive Crosstalk OdBm0 Transmit Level	f=300 Hz - 3 400 Hz DR = Steady PCM Code		-90	-75	dB
CT _R -X	Receive to Transmit Crosstalk odBm0 Receive Level	f=300 Hz - 3 400 Hz VFxI' = OV		-90	-70	dB

Note 1: Quantization Noise, measured by extrapolation from the distortion result. Note 2: Idle Channel Noise, due to alternating sign bit of a perfectly zeroed encoder.



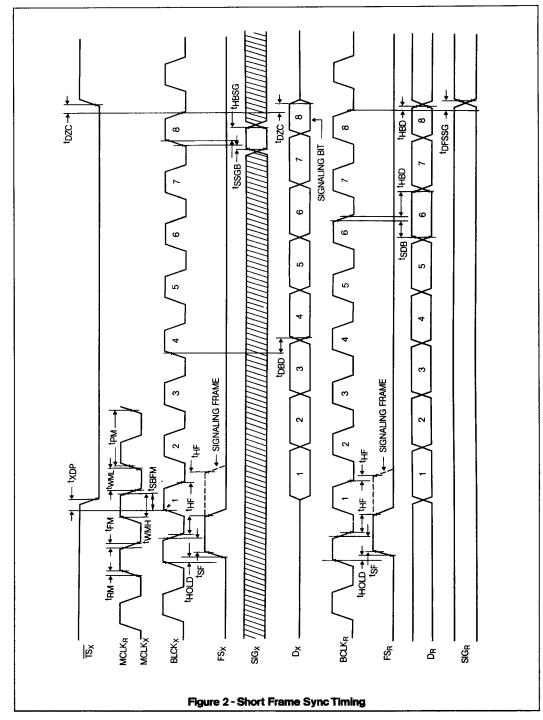
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TIMING SPECIFICATIONS

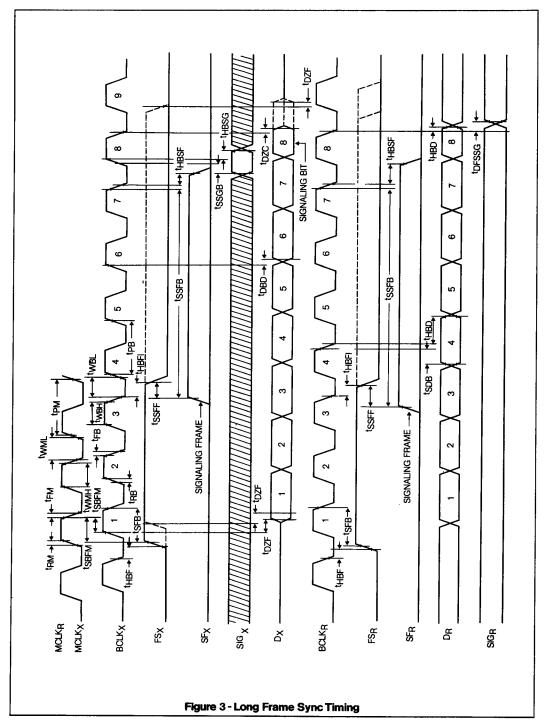
Unless otherwise specified TA = -40 °C to 85 °C, V_{CC} = $5V \pm 5$ %, V_{BB} = $-5V \pm 5$ %, GND = 0V

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
1/tpM	Frequency of Master Clocks	Depends on the Device Used and the BCLKR/CLKSEL Pin MCLKx and MCLKR		1.536 1.544 2.048		MHz MHz MHz
tWMH	Width of Master Clock High	MCLK _X and MCLK _R	160			ns
tWML	Width of Master Clock Low	MCLKx and MCLKR	160			ns
tsbfM	Set-Up Time from BCLKx High (and FSx in Long Frame Sync Mode) to MCLKx Falling Edge	First Bit Clock after the Leading Edge of FSX	100			ns
tWBH	Width of Bit Clock High	V _{IH} =2.2V	160			ns
tWBL	Width of Bit Clock Low	V _{IL} = 0.6V	160			ns
tHBF	Holding Time from Bit Clock Low to Frame Sync	Long Frame Only	0			ns
tHOLD	Holding Time from Bit Clock High to Frame Sync	Short Frame Only	0			ns
tsBF	Set-Up Time from Frame Sync to Bit Clock Low	Long Frame Only	80			ns
tDBD	Delay Time from BCLKx High to Data Valid	Load = 150 pF plus 2 LSTTL loads	0		140	ns
tXDP	Delay Time to TSX Low	Load=150 pF plus 2 LSTTL loads			140	ns
tDZC	DelayTime from BCLKx Low to Data Output Disabled	C _L =0 pF to 150 pF	50		165	ns
tDZF	Delay Time to Valid Data from FSx or BCLKx, Whichever Comes later	CL = 0 pF to 150 pF	20	į	165	ns
tssff	Set-Up Time from SFX/R High to FSX/R	HC 3053 Only	60			ns
tssfb	Set-Up Time from Signal Frame Sync High to BCLKX/R Clock	HC 3053 Only	60			ns
tSSGB	Set-UpTimefromSIGXtoBCLKX	HC 3052 and HC 3053	100			ns
tHBSG	Hold Time from BCLKx High to SIGx	HC 3052 and HC 3053	50			ns
tSDB	Set-Up Time from DRValid to BCLKR/X Low		50			ns
tHBD	Hold Time from BCLKR/X Low to DR Invalid		50			ns
tHBSF	Hold Time from BCLKX/R Low to Signaling Frame Sync	HC 3053 Only	100			ns
tSF	Set-Up Time from FSx/R to BCLKx/R Low	Short Frame Sync Pulse (1 Bit Clock Period Long)	50			ns
tHF	Hold Time from BCLKX/R Low to FSX/R Low	Short frame Sync Pulse (1 Bit Clock Period Long)	100			ns
tHBFI	Hold Time from 3rd Period of Bit Clock Low to Frame Sync (FSX or FSR)	Long Fram Sync Pulse (from 3 to 8 Bit Clock Periods Long)	100			ns
tWFL	Minimum Width of the Frame Sync Pulse (Low Level)	64K Bit/s Operating Mode	160			ns









OPERATING INSTRUCTIONS

Ground should be applied to the device before any other connection. Although VCC and VBB can be connected in any order, one should check that voltages on all inputs and on supply rails stay within absolute maximum ratings even for very short periods to avoid any latch-up. All ground connections to each

device should meet at a common point as close as possible to the GND pin.

Two 0.1 µ Fdecoupling capacitors are required from the

common ground point to VCC and VBB.
The ground point of each COFIDEC should be tied to a common card ground in star formation, rather than via a ground bus.

